



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
United States Patent and Trademark Office
Address: COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, Virginia 22313-1450
www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/774,115	02/06/2004	Glen C. Shepherd	Solectron 735	8375
7590	06/27/2006		EXAMINER	
Robert Moll 1173 St. Charles Court Los Altos, CA 94024			DINH, TUAN T	
			ART UNIT	PAPER NUMBER
			2841	

DATE MAILED: 06/27/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

10/774,115

Applicant(s)

SHEPHERD ET AL.

Examiner

Tuan T. Dinh

Art Unit

2841

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 13 April 2006.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-35 is/are pending in the application.
- 4a) Of the above claim(s) 30-35 is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-29 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
 - ☐ Certified copies of the priority documents have been received in Application No. _____.
 - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☒ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date 09/01/04.

- 4) ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____.
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: _____.

DETAILED ACTION

1. Applicant's election without traverse of Group I (claims 1-29) in the reply filed on 04/13/06 is acknowledged.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

3. Claims 1-2, 9-15, and 22-29 are rejected under 35 U.S.C. 102(b) as being anticipated by Swamy (US 5,459,287).

As to claim 1, Swamy discloses a substrate (30) as shown in figures 1-4 with a via and pad structure, comprising:

a substrate (30, column 4, line 40),

a plated via (44, column 4, line 57) connected to conductive layers (40, 42, column 4, lines 60-61),

a solder mask (52, 54, column 4, lines 17-18) surrounding the plated via (44);
and

a conductive pad (48a) with a conductive trace connected to the plated via, wherein the conductive pad extends beyond the terminal sides (solder ball) of a component (BGA package 32) to increase solder formation at the terminal sides.

As to claim 14, Swamy discloses a substrate (30) with a plurality of via and pad structures as shown in figures 1-4, comprising: a substrate (30), first and second plated vias (44) connected to the conductive layers (40, 42), first and second solder masks (52, 54) surrounding the first and second plated vias (44); first and second conductive pads (48a) each with a conductive trace connected to the first and second plated vias (44), wherein the first and second conductive pad extends beyond the terminal sides of the component to increase solder formation along the terminal sides.

As to claims 2, 15, Swamy discloses the solder mask (52, 54) reduces solder formation at the terminal end of the component (32).

As to claims 9-11, 22-25, 29, Swamy discloses the solder mask (52, 54) is a ring or keyhole shaped, the solder mask covers the substrate partially or entirely except the conductive pad and the plated via, and further comprising a component (32) electrically connected to the conductive pad through solder joint(s) (46), wherein the solder joints have a greater volume at the terminal sides than at the terminal end of the component.

As to claim 12-13, 27-28, Swamy discloses the substrate (30) is part of a printed circuit board or a BGA package

As to claim 26, Swamy discloses the separation along the substrate (30) between the first and second solder masks (52, 54) defines the length of the component to be soldered.

Claim Rejections - 35 USC § 103

4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

5. Claims 3-8, and 16-21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Swamy ('287) in view of Osann, Jr. et al. (US 5,384,433).

As to claims 3-8, and 16-21, Swamy does not disclose the conductive pad including first and second arms and a body or a T-shaped structure that extend beyond the terminal sides of the component, the first arm and the second arm are symmetrically disposed on the substrate with respect to the plated via.

Osann, Jr. et al. teach a pad structure (see figure 2) having two arms and a body or a T-shaped pad structure that extend beyond the terminal sides of the component, the first arm and the second arm are symmetrically disposed on the substrate with respect to the plated via.

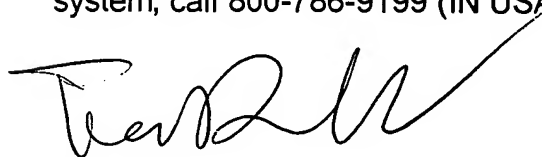
It would have been obvious to one having ordinary skill in the art at the time the invention was made to have a teaching of Osann employed in the pad structure of Swamy in order to provide strong bonding and electrical connection between components and a board.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan T. Dinh whose telephone number is 571-272-1929. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kammie Cuneo can be reached on 571-272-1957. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.



Tuan Dinh
June 20, 2006.